

Dr SATYANARAYAN

List of Publications by Year in descending order

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20
papers

324
citations

1039406

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g-index

20
all docs

20
docs citations

20
times ranked

289
citing authors

#	ARTICLE	IF	CITATIONS
1	An influence of substrate thickness on electrical conductivity of dip-soldered copper joints. Journal of Mines, Metals and Fuels, 2022, 69, 255.	0.0	0
2	A review on effect of alloying elements and heat treatment on properties of Al- Sn alloy. Materials Today: Proceedings, 2021, 35, 340-343.	0.9	0
3	A Review of the Performance and Characterization of Conventional and Promising Thermal Interface Materials for Electronic Package Applications. Journal of Electronic Materials, 2019, 48, 7623-7634.	1.0	55
4	The Effect of Thermal Ageing on Solder/Substrate Interfacial Microstructures During Reflow of Sn-37Pb and Sn-3Ag-0.5Cu. Transactions of the Indian Institute of Metals, 2019, 72, 1545-1549.	0.7	2
5	Effect of Cooling Medium on Microstructure, Impact and Hardness Properties of Al-15Sn Alloy. Transactions of the Indian Institute of Metals, 2019, 72, 1941-1947.	0.7	2
6	Underwater shock wave weldability window for Sn-Cu plates. Journal of Materials Processing Technology, 2019, 267, 152-158.	3.1	18
7	Welding of Sn and Cu plates using controlled underwater shock wave. Journal of Materials Processing Technology, 2017, 245, 300-308.	3.1	25
8	Solder Joint Reliability of Sn-Cu and Sn-Ag-Cu Lead-Free Solder Alloys Solidified on Copper Substrates with Different Surface Roughnesses. Materials Science Forum, 2015, 830-831, 265-269.	0.3	1
9	Effect of reflow temperature and substrate roughness on wettability, IMC growth and shear strength of SAC387/Cu bonds. Journal of Materials Science: Materials in Electronics, 2014, 25, 864-872.	1.1	9
10	Reactive wetting of Sn-2.5Ag-0.5Cu solder on copper and silver coated copper substrates. Journal of Materials Science: Materials in Electronics, 2013, 24, 1714-1719.	1.1	5
11	Spreading Behavior and Evolution of IMCs During Reactive Wetting of SAC Solders on Smooth and Rough Copper Substrates. Journal of Electronic Materials, 2013, 42, 2696-2707.	1.0	8
12	Effect of Purging Gas on Wetting Behavior of Sn-3.5Ag Lead-Free Solder on Nickel-Coated Aluminum Substrate. Journal of Materials Engineering and Performance, 2013, 22, 723-728.	1.2	7
13	Wettability of root canal sealers on intraradicular dentine treated with different irrigating solutions. Journal of Dentistry, 2013, 41, 556-560.	1.7	45
14	Solder joint reliability of Sn-0.7Cu and Sn-0.3Ag-0.7Cu lead-free solder alloys solidified on copper substrates with different surface roughnesses. Materials Science and Technology, 2013, 29, 1430-1440.	0.8	4
15	Wetting Characteristics of Sn-0.7Cu Lead-Free Solder Alloy on Copper Substrates. Materials Science Forum, 2012, 710, 569-574.	0.3	3
16	Effect of temperature and substrate surface texture on wettability and morphology of IMCs between Sn-0.7Cu solder alloy and copper substrate. Journal of Materials Science: Materials in Electronics, 2012, 23, 1664-1672.	1.1	12
17	Wetting Behavior and Evolution of Microstructure of Sn-3.5Ag Solder Alloy on Electroplated 304 Stainless Steel Substrates. Transactions of the Indian Institute of Metals, 2012, 65, 713-717.	0.7	3
18	Effect of cooling rate during solidification of Sn-9Zn lead-free solder alloy on its microstructure, tensile strength and ductile-brittle transition temperature. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2012, 533, 64-70.	2.6	36

#	ARTICLE	IF	CITATIONS
19	Wetting behaviour and interfacial microstructure of Sn–Ag–Zn solder alloys on nickel coated aluminium substrates. <i>Materials Science and Technology</i> , 2011, 27, 1157-1162.	0.8	14
20	Reactive wetting, evolution of interfacial and bulk IMCs and their effect on mechanical properties of eutectic Sn–Cu solder alloy. <i>Advances in Colloid and Interface Science</i> , 2011, 166, 87-118.	7.0	75